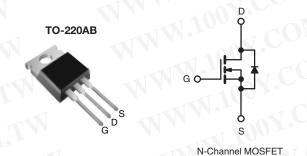


Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) 500				
R _{DS(on)} (Ω)	V _{GS} = 10 V	0.85		
Q _g (Max.) (nC)	38			
Q _{gs} (nC)	9.0			
Q _{gd} (nC)	18			
Configuration	Sing	le le		



FEATURES

 Low Gate Charge Q_g Results in Simple Drive Requirement



- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- RoHS*
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Effective Coss Specified
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptable Power Supply
- High Speed Power Switching

TYPICAL SMPS TOPOLOGIES

- Two Transistor Forward
- Half Bridge
- Full Bridge

ORDERING INFORMATION	NY.CO TY	111111111111111111111111111111111111111
Package	TO-220AB	
Load (Dh.) fund	IRF840APbF	
Lead (Pb)-free	SiHF840A-E3	
SnPb	IRF840A	
SIIFD	SiHF840A	

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unle	ess otherwis	e noted)		
PARAMETER	10	17.	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	XIVI . I	-10	V _{DS}	500	
Gate-Source Voltage	- 4		V _{GS}	± 30	V
Continuous Drain Current	$T_C = 25 ^{\circ}\text{C}$		- () [A]	8.0	
Continuous Drain Current	V _{GS} at 10 V	$T_C = 25 \degree C$ $T_C = 100 \degree C$	ID	5.1	А
Pulsed Drain Current ^a	TIN	Too	I _{DM}	32	
Linear Derating Factor		001		1.0	W/°C
Single Pulse Avalanche Energy ^b		1100	E _{AS}	510	mJ
Repetitive Avalanche Currenta	-11	- 01	I _{AR}	8.0	Α
Repetitive Avalanche Energy ^a		1100 T	E _{AR}	13	mJ
Maximum Power Dissipation $T_C = 25 ^{\circ}C$		P _D	125	W	
Peak Diode Recovery dV/dt ^c		-7.10	dV/dt	5.0	V/ns
perating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature)	for 1	0 s		300 ^d	
Mounting Torque	6-32 or M	2 corour		10	lbf ⋅ in
Mounting Torque	0-32 OF IVI	3 Screw		1.1	N⋅m

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 16 mH, R_g = 25 Ω , I_{AS} = 8.0 A (see fig. 12).
- c. $I_{SD} \le 8.0$ A, $dI/dt \le 100$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C.
- d. 1.6 mm from case.

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^{*} Pb containing terminations are not RoHS compliant, exemptions may apply

IRF840A, SiHF840A

Vishay Siliconix

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THERMAL RESISTANCE RAT	THE WAY	V.Cor		
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}		62	of Co.
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50		°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	T T	1.0	

SPECIFICATIONS (T _J = 25 °C, u	nless otherw	rise noted)				J.V.	
PARAMETER	SYMBOL	TEST	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static	~1 C	Oh-	N «X				
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0$) V, I _D = 250 μA	500	1-1	JU	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 1 mA		0.58	~55	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V$	I_{GS} , $I_{D} = 250 \mu A$	2.0	-45]	4.0	٧
Gate-Source Leakage	I _{GSS}	V _G	$_{\rm GS} = \pm 30 \text{ V}$		1	± 100	nA
Zero Gate Voltage Drain Current	41 10U 3	$V_{DS} = 5$	00 V, V _{GS} = 0 V	-	-737	25	μA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 400 \text{ V}, \text{ V}$	V _{GS} = 0 V, T _J = 125 °C	-	N- 1	250	μΑ
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	$I_D = 4.8 \text{ A}^b$	-		0.85	Ω
Forward Transconductance	9 _{fs}	$V_{DS} = 5$	60 V, I _D = 4.8 A ^b	3.7	TH	-	S
Dynamic	-<1 10	0 3.	M_{i}			-XXI 1	$I_{\Omega\Omega}$
Input Capacitance	C _{iss}		/ _{GS} = 0 V,	-	1018	4-1	
Output Capacitance	C _{oss}	V	_{DS} = 25 V,	-	155		10
Reverse Transfer Capacitance	C _{rss}	f = 1.0	MHz, see fig. 5	-	8.0	11-4.	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V; } V_{D}$	_S = 1.0 V, f = 1.0 MHz		1490	-73	pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}; V_{DS}$	_S = 400 V, f = 1.0 MHz		42		
Effective Output Capacitance	C _{oss} eff.	$V_{GS} = 0 \text{ V};$	V _{DS} = 0 V to 400 V ^c		56		XXI
Total Gate Charge	Qg		COL	-		38	4
Gate-Source Charge	Q_{gs}	V _{GS} = 10 V	$I_D = 8 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 ^b	-	_	9.0	nC
Gate-Drain Charge	Q_{gd}	11.2	occ rig. o and ro	1 -	_	18	
Turn-On Delay Time	t _{d(on)}	-31100		-	11	-	-7
Rise Time	t _r	V _{DD} =	250 V, I _D = 8 A	KN I	23	-41	
Turn-Off Delay Time	t _{d(off)}	$R_g = 9.1 \Omega, R$	$I_D = 31 \Omega$, see fig. 10^b	-	26	-	ns
Fall Time	t _f				19	- <	
Drain-Source Body Diode Characteristic	s	-311	July - OW	7		•	
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the			-	8.0	A
Pulsed Diode Forward Current ^a	I _{SM}	integral reverse p - n junction di	ode		N-	32	
Body Diode Voltage	V_{SD}	T _J = 25 °C,	$I_S = 8 \text{ A}, V_{GS} = 0 \text{ V}^b$	110	-	2.0	V
Body Diode Reverse Recovery Time	t _{rr}	T - 05 °C 1	0 A dl/dt - 100 A/:-ah	- 7	422	633	ns
Body Diode Reverse Recovery Charge	Q _{rr}	13 = 25 °C, I _F =	= 8 A, dl/dt = 100 A/µsb	II T \cdot	2.16	3.24	μC
Forward Turn-On Time	t _{on}	Intrinsic turn	-on time is negligible (turn	-on is do	minated b	y L _S and	L _D)

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.
- c. C_{oss} eff. is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

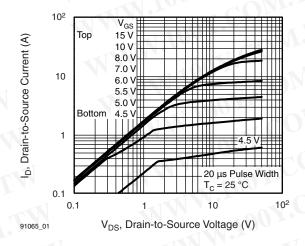


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

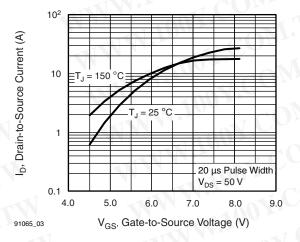


Fig. 3 - Typical Transfer Characteristics

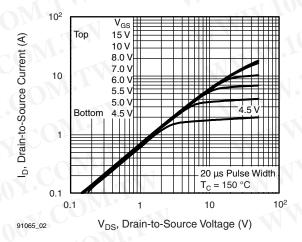


Fig. 2 - Typical Output Characteristics, T_C = 150 °C

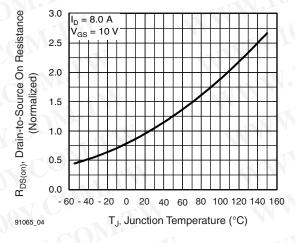


Fig. 4 - Normalized On-Resistance vs. Temperature



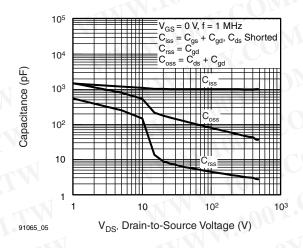


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

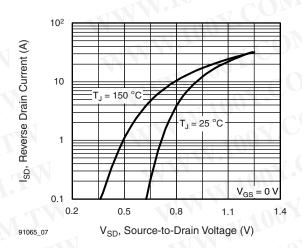


Fig. 7 - Typical Source-Drain Diode Forward Voltage

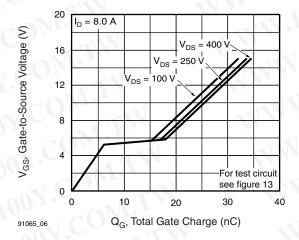


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

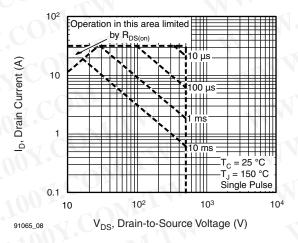


Fig. 8 - Maximum Safe Operating Area

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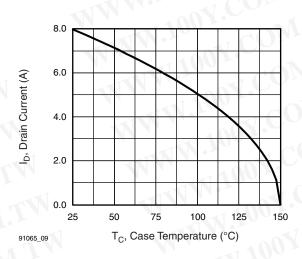


Fig. 9 - Maximum Drain Current vs. Case Temperature

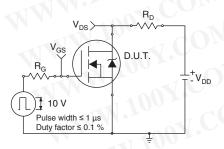


Fig. 10a - Switching Time Test Circuit

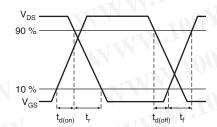


Fig. 10b - Switching Time Waveforms

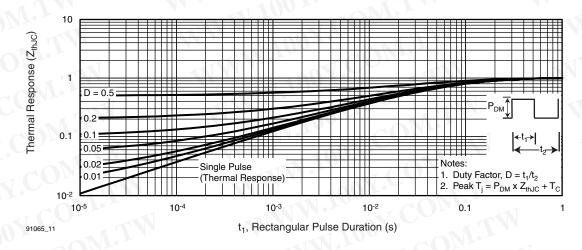


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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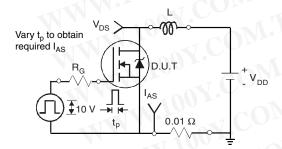


Fig. 12a - Unclamped Inductive Test Circuit

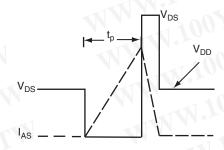


Fig. 12b - Unclamped Inductive Waveforms

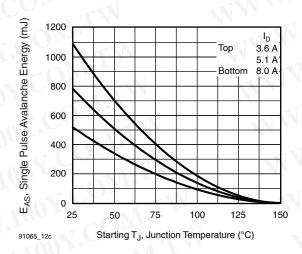


Fig. 12c - Maximum Avalanche Energy vs. Drain Current



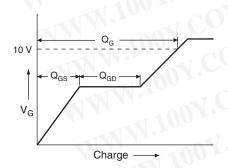


Fig. 12d - Basic Gate Charge Waveform

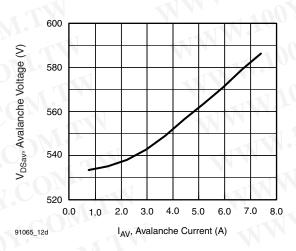


Fig. 13a - Typical Drain-to-Source Voltage vs. Avalanche Current

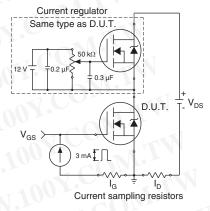
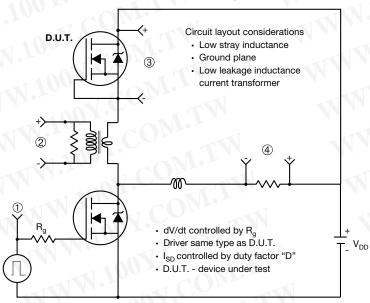


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



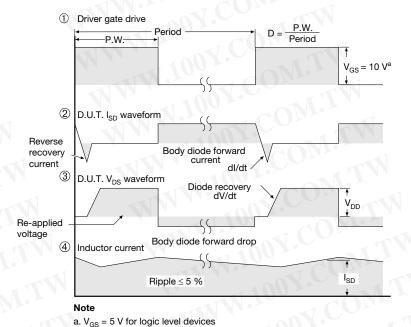


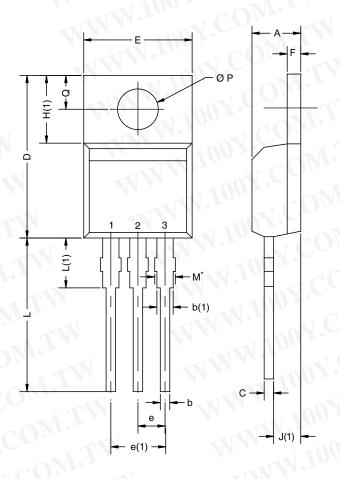
Fig. 14 - For N-Channel

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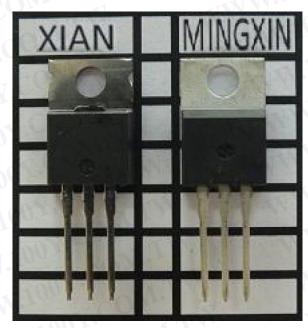
TO-220AB



4	MILLIN	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

Notes

- * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM
- Xi'an and Mingxin actual photo



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Revision: 02-Oct-12 Document Number: 91000